

	U	1 Document ID	Issue Date	Pages	Title	Current OR	Current XRef 🛕
1	С	☐ US 20040145039 A1	20040729	17	Stacked semiconductor packages and method for the fabrication thereof	257/678	438/106
2	П	☐ US 20040140552 A1	20040722	35	Semiconductor device	257/700	
3	С	☐ US 20040124518 A1	20040701	47	Semiconductor stacked multi-package module having inverted second package	257/686	257/738; 438/109;
4		r US 20040119153 A1		47	Semiconductor multi-package module having inverted land grid array (LGA)	257/686	257/659; 257/706;
5	C	□ US 20040119152 A1	20040624	46	Semiconductor multi-package module having inverted bump chip carrier second	257/686	257/784; 438/109
6	Γ	☐ US 20040113275 A1	20040617	47	Semiconductor multi-package module having inverted second package stacked	257 <i>[7</i> 58	
7	P	☐ US 20040113255 A1	20040617	46	Semiconductor multi-package module having inverted second package and	257/686	438/109
9	V	☐ US 20040113254 A1	20040617	47	Semiconductor multi-package module having inverted second package stacked	257/686	257/659; 257/728;
9		☐ US 20040113253 A1		46	:Semiconductor stacked multi-package module having inverted second package	257/686	
10		US 20040067606 A1	20040408	9	Method for stack-packaging integrated circuit die using at least one die in the	438/109	438/127
11 •	г	□ US 20040065963 A1	20040408	36	Semiconductor multi-package module having wire bond interconnect between	257/777	.,